

# Fred Barlow

## List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/11924602/publications.pdf>

Version: 2024-02-01

14  
papers

471  
citations

1937685  
4  
h-index

1588992  
8  
g-index

14  
all docs

14  
docs citations

14  
times ranked

405  
citing authors

#	ARTICLE	IF	CITATIONS
1	Delay estimation using SVD-based causal fourier continuations for high speed interconnects. , 2016, , .		0
2	Time Delay Extraction from Frequency Domain Data Using Causal Fourier Continuations for High-Speed Interconnects. Electronics (Switzerland), 2015, 4, 799-826.	3.1	3
3	Delay estimation using SVD-based causal fourier continuations for high speed interconnects. , 2015, , .		0
4	Causality Verification Using Polynomial Periodic Continuations for Electrical Interconnects. Journal of Microelectronics and Electronic Packaging, 2014, 11, 181-196.	0.7	6
5	Causality Enforcement of High-Speed Interconnects via Periodic Continuations. International Symposium on Microelectronics, 2014, 2014, 000236-000241.	0.0	4
6	A new method for causality enforcement of DRAM package models using discrete hilbert transforms. , 2013, , .		2
7	Development of a SiC JFET-Based Six-Pack Power Module for a Fully Integrated Inverter. IEEE Transactions on Power Electronics, 2013, 28, 1464-1478.	7.9	125
8	Evaluation of Direct Bond Aluminum Substrates for Power Electronic Applications in Extreme Environments. Additional Conferences (Device Packaging HiTEC HiTEN & CICMT), 2012, 2012, 000012-000017.	0.2	1
9	Implementation of a fully integrated 50 kW inverter using a SiC JFET based six-pack power module. , 2011, , .		7
10	Waveguide Inductive Strip Filter Embedded in LTCC. Additional Conferences (Device Packaging HiTEC) Tj ETQq0 0 0 rgBT /Overlock 10 T	0.2	0
11	Evaluation of Ceramic Substrates for High Power and High Temperature Applications. Additional Conferences (Device Packaging HiTEC HiTEN & CICMT), 2011, 2011, 000199-000206.	0.2	2
12	18 kW three phase inverter system using hermetically sealed SiC phase-leg power modules. , 2010, , .		36
13	Fabrication of Precise Fluidic Structures in LTCC. International Journal of Applied Ceramic Technology, 2009, 6, 18-23.	2.1	25
14	Power Conversion With SiC Devices at Extremely High Ambient Temperatures. IEEE Transactions on Power Electronics, 2007, 22, 1321-1329.	7.9	260